

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

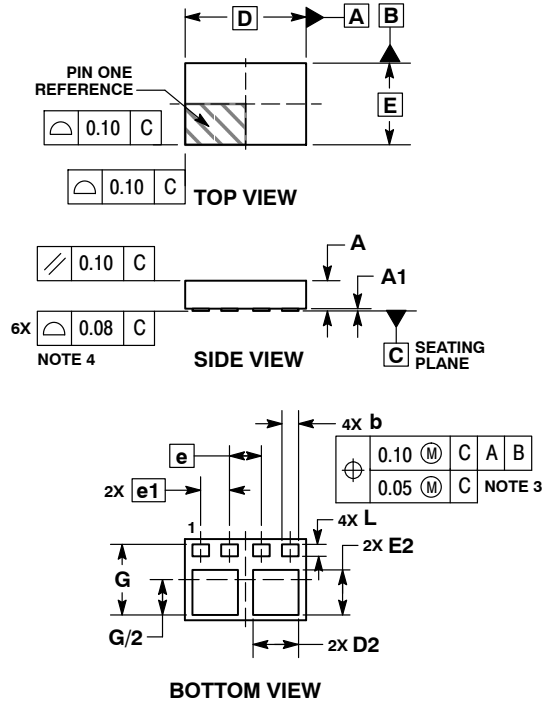
ON Semiconductor®



SCALE 4:1

**XDFN4 2.0x1.35, 0.525P**  
CASE 711BD  
ISSUE O

DATE 15 SEP 2015

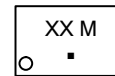


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE PADS AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.34	0.44
A1	0.00	0.05
b	0.225	0.325
D	2.00 BSC	
D2	0.70	0.80
E	1.35 BSC	
E2	0.70	0.80
e	0.525 BSC	
e1	0.475 BSC	
G	1.12	1.23
L	0.15	0.25

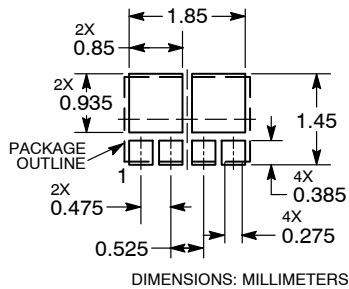
**GENERIC MARKING DIAGRAM\***



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT**



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<b>DESCRIPTION:</b>	<b>XDFN4 2.0X1.35, 0.525P</b>	<b>PAGE 1 OF 1</b>

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